

WSK063

半导体晶圆切片机

WSK063 SiC slicing machine (slurry cutting)



技术规格参数 Specifications and Technical Parameters

工件 workpiece	
横断面 cross section	≤Φ330mm
长度 length	2×300mm; 1×600mm
厚度 thickness	0.20200mm (必须调整制程 must adjust manufacturing process)
切割速率 cutting rate	
线速度 linear velocity	最大 max 200x/min 速度可调 can set
快速移动 fast move	200mm/min
工作行程 working stroke	最大 MAX 385mm
钢线 wire	
芯线径 diameter of core wire (external diameter)	0.055-0.400mm
钢线长度 length of wire	按线轮而定 according to wire wheel
钢线方向 direction of wire	前进或后退切割 forward or backward/double directional cutting
预先张力 pre-tension	最大 50N (端视钢线直径而定) max 50N (according to diameter of wire)
导轮 guide wheel	
直径 diameter	Φ192mm
长度 length	662mm
个数 number	3
主电机功率 main motor power	最大 max 3x30KW
轴距 (左右) wheelbase (left & right)	540mm
轴距 (上下) wheelbase (up & down)	450mm
钢线偏向滚轮 offset roller	
直径 diameter	160mm
个数 number	2×3(0)
卷绕线盘 winding coil	
卷绕轴工作高度 working height of winding shaft	1355mm
地线盘 winding coil	WSK02WSJ2750, 21, 201
地线盘卷绕数 winding coil number	1A, 011
切削液供应 cutting compound supply	
切削液流量最大容量 capacity of cutting fluid tank	1000L
切削液温度常数 temperature constant of cutting fluid tank	可选择预设温度 optional preset temperature 20-70°C
泵浦输洋率 pump rate	最大 MAX 12000L/h 可以调整, 使用流量计测量 adjustable, measure with flow meter and display
冷却水流入温度 inflow temperature of cooling water	15°C ± 1°
切削液冷却系统 cutting fluid cooling system	
安全 type	SP3 控制板 PLC 控制板 GPC 控制板 G7 系列 PLC 控制板 G7 series with integrated PLC
供货商 supplier	西门子 (Siemens)
工作面板 work panel	钢化玻璃板 safety glass screen
外观尺寸及总重量 outline dimension and total weight	
长度 length	4700mm
宽度 width	2170mm
高度 height	3500mm
总重量 total weight	约 13000kg

设备用途和特性

- 本机适用于半导体行业用半导体晶圆切片机是半导体行业硅片加工的主要配套设备。硅锭横断面最大为Φ330mm，切片厚度最小为0.2mm，必须调整制程，一次装夹最大可切片达1300-2000片是半导体硅片生产厂家的优选设备。
- 本机床特点：
 - 1、两个钢线导轮驱动 收（放）线驱动 及收（放）线的排线驱动，均采用伺服驱动，且可双向运行。
 - 2、钢线张紧力的检测控制也通过伺服电机驱动（恒张力、恒速度）。
 - 3、工件进给由伺服电机通过滚珠丝杆拖动，进给量的大小与钢线的引导速度相匹配。
 - 4、切削液的搅拌与输送。切削液管道通过热交换器达到恒温及计量器计量，与切片速度相匹配。
 - 5、本机床为高新技术集中的产品。

Applications and structural features

- the machine is used for cutting semiconductor bar, which is main matched processing equipment. The max dimension of cross section Φ330mm, the minimum thickness of section 0.2mm, adjust processing procedure, it may cut 1300-2000 pieces at one time, being the optimized equipment for semiconductor manufacturers.
- features:
 - two wire guide wheel drive, spool & pay-off drive, cable drive, all of these apply servo motor and must be constant speed.
 - detection control of wire tension and be controlled by servo motor (constant force).
 - workpiece feed is driven by servo motor through ball screw, feed rate is matched with guiding speed of wire.
 - agitation and conveying of cutting fluid. Cutting fluid pipe can reach up constant temperature through heat exchanger, matching the slicing rate.
 - this machine is an integrated high-tech product.

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